

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-23. (canceled)

24. (currently amended) A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a conductive material;
rear connectors mounted at the rear wall; and
at least one receptacle defined through the front wall for receiving a circuit component, the receptacle having a depth of sufficient magnitude to choke emissions generated within the housing;

wherein the front wall is configured to choke RF emissions to a level such that the module radiates signals that are 100 db down or better from a carrier across a frequency range of 5 megahertz to 1 gigahertz, even in the absence of covers; and
wherein the depth is greater than .15 inches.

25. (original) The module of claim 24, further comprising a front connector positioned within the housing for interfacing with the circuit component, wherein the receptacle is adapted to guide the circuit component into the front connector.

26. (original) The module of claim 24, further comprising a plurality of the receptacles for receiving a plurality of circuit components, each receptacle having a depth of sufficient magnitude to choke emissions generated within the housing.

27. (canceled)

28. (canceled)

29. (previously presented) The module of claim 24, wherein the depth is at least .2 inches.

30. (previously presented) The module of claim 24, wherein the depth is at least .3 inches.
31. (original) The module of claim 24, further comprising a cover adapted to be mounted over the receptacle.
32. (original) The module of claim 31, wherein the cover includes metal.
33. (original) The module of claim 31, wherein the cover includes a non-conductive material.
34. (original) The module of claim 31, wherein the cover includes plastic.
35. (original) The module of claim 31, wherein the cover includes at least a portion that is transparent.
36. (previously presented) The module of claim 24, wherein the circuit component or components include attenuator pads.
37. (original) The module of claim 36, further comprising a cover for covering the attenuator pads, the cover being configured such that attenuation values of the attenuator pads can be determined without removing the cover from the housing.
38. (original) The module of claim 24, wherein the module comprises splitter/combiner module and includes splitter/combiner circuitry, and wherein the circuit component comprises an attenuator pad.
39. (canceled)
40. (canceled)

41. (original) A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a conductive material;
rear connectors mounted at the rear wall;
at least one receptacle defined through the front wall for receiving a circuit component;
and
a non-metallic cover for covering the receptacle.
42. (original) The module of claim 31, further comprising splitter/combiner circuitry positioned within the housing, and wherein the circuit component comprises an attenuator pad.
43. (original) The module of claim 42, wherein the cover includes at least a portion that is transparent.
44. (canceled)